

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	85	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	60	V
Forward Continuous Current	I _{FM}	160	mA
(Note 5)		140	
Repetitive Peak Forward Current (Note 5)	I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	4.0	A
@ t = 1.0μs		1.0	
@ t = 1.0ms		0.5	
@ t = 1.0s			

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	85	—	—	V	I _R = 100μA
Forward Voltage	V _F	—	—	0.90 1.0 1.1 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Leakage Current (Note 6)	I _R	—	—	5.0 80	nA nA	V _R = 75V V _R = 75V, T _J = 150°C
Total Capacitance	C _T	—	3	—	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	3.0	μs	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

Notes: 5. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.

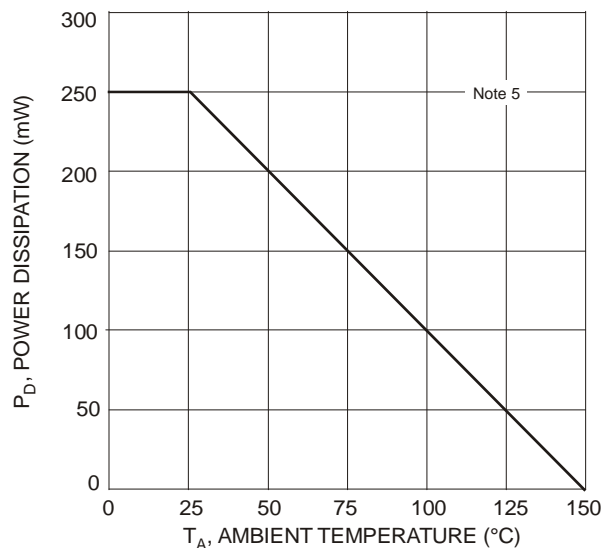


Fig. 1 Power Derating Curve, Total Package

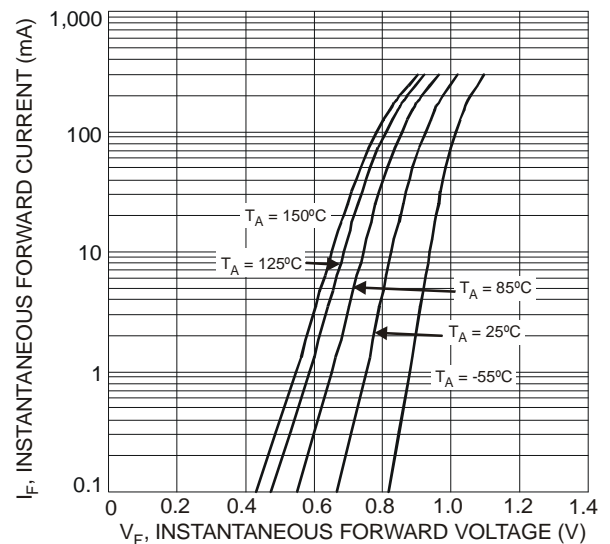


Fig. 2 Typical Forward Characteristics, Per Element

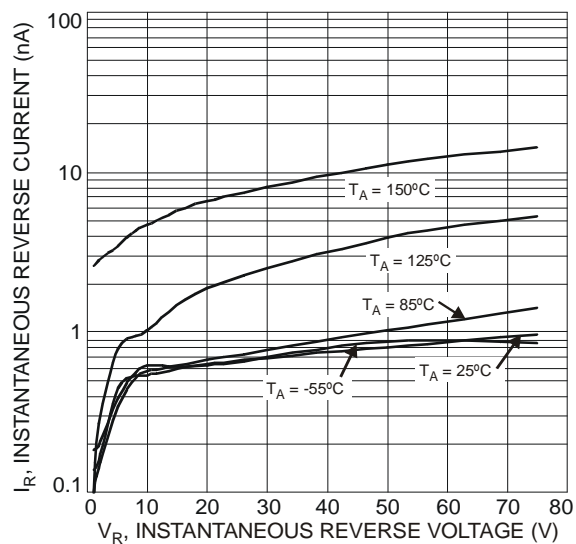


Fig. 3 Typical Reverse Characteristics, Per Element

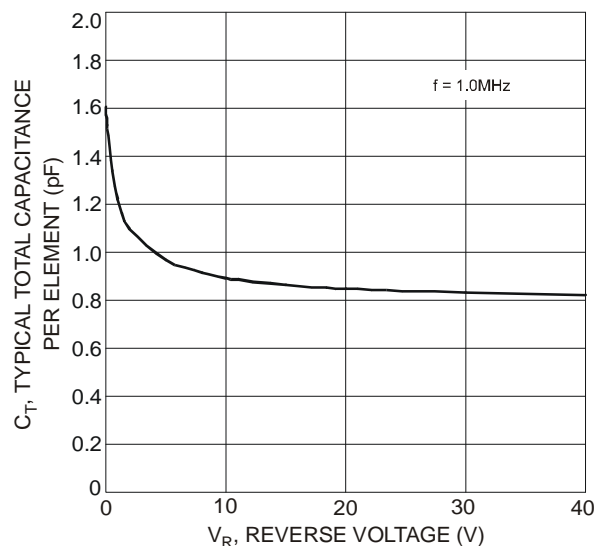
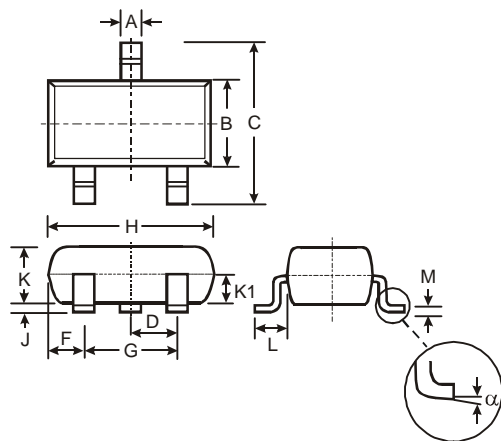


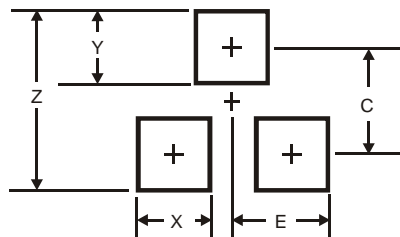
Fig. 4 Typical Capacitance vs. Reverse Voltage

Package Outline Dimensions



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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